



Method and Circuit Board for Assembling Electronic Devices

Abstract

Disclosed is a method and a circuit board for assembling electronic devices. The circuit board comprises a plurality of soldering pads for soldering contacts of electronic devices, and at least an insulated zone neighboring at least one of the soldering pads, from which soldering paste is extendible to at least a portion of the insulated zone while applying soldering paste. The method disclosed in this invention comprises the steps of, on a circuit board having a plurality of soldering pads, applying soldering paste onto at least a portion of the soldering pads allowing the soldering paste to extend outwardly from at least one soldering pad to locations not in contact with other soldering pads or traces, or to at least a portion of an insulated zone neighboring the soldering pad; and soldering contacts of electronic devices to the circuit board having the portion of soldering pads including the at least one soldering pad.

Figures 3(a) to 3(d)